

8-bit CMOS Microcontroller ROMless

1. Description

TS80C31X2 is high performance CMOS and ROMless versions of the 80C51 CMOS single chip 8-bit microcontroller.

The TS80C31X2 retains all features of the TSC80C31 with 128 bytes of internal RAM, a 5-source, 4 priority level interrupt system, an on-chip oscilator and two timer/counters.

In addition, the TS80C31X2 has a dual data pointer, a more versatile serial channel that facilitates multiprocessor communication (EUART) and a X2 speed improvement mechanism.

The fully static design of the TS80C31X2 allows to reduce system power consumption by bringing the clock frequency down to any value, even DC, without loss of data.

The TS80C31X2 has 2 software-selectable modes of reduced activity for further reduction in power consumption. In the idle mode the CPU is frozen while the timers, the serial port and the interrupt system are still operating. In the power-down mode the RAM is saved and all other functions are inoperative.

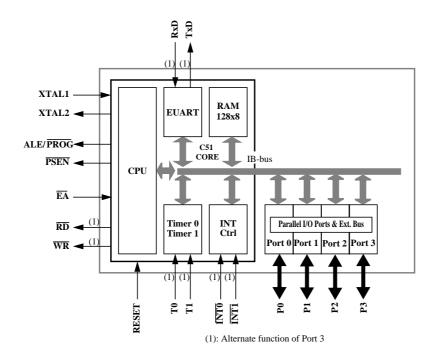
2. Features

- 80C31 Compatible
 - 8031 pin and instruction compatible
 - Four 8-bit I/O ports
 - Two 16-bit timer/counters
 - 128 bytes scratchpad RAM
- High-Speed Architecture
 - 40 MHz @ 5V, 30MHz @ 3V
 - X2 Speed Improvement capability (6 clocks/ machine cycle)
 - 30 MHz @ 5V, 20 MHz @ 3V (Equivalent to 60 MHz @ 5V, 40 MHz @ 3V)
- Dual Data Pointer
- Asynchronous port reset

- Interrupt Structure with
 - 5 Interrupt sources,
 - 4 priority level interrupt system
- Full duplex Enhanced UART
 - Framing error detection
 - Automatic address recognition
- Power Control modes
 - Idle mode
 - Power-down mode
 - · Power-off Flag
- Once mode (On-chip Emulation)
- Power supply: 4.5-5.5V, 2.7-5.5V
- Temperature ranges: Commercial (0 to 70°C) and Industrial (-40 to 85°C)
- Packages: PDIL40, PLCC44, VQFP44 1.4, PQFP F1 (13.9 footprint)



3. Block Diagram





4. SFR Mapping

The Special Function Registers (SFRs) of the TS80C31X2 fall into the following categories:

• C51 core registers: ACC, B, DPH, DPL, PSW, SP, AUXR1

• I/O port registers: P0, P1, P2, P3

• Timer registers: TCON, TH0, TH1, TMOD, TL0, TL1

• Serial I/O port registers: SADDR, SADEN, SBUF, SCON

Power and clock control registers: PCON

• Interrupt system registers: IE, IP, IPH

• Others: CKCON

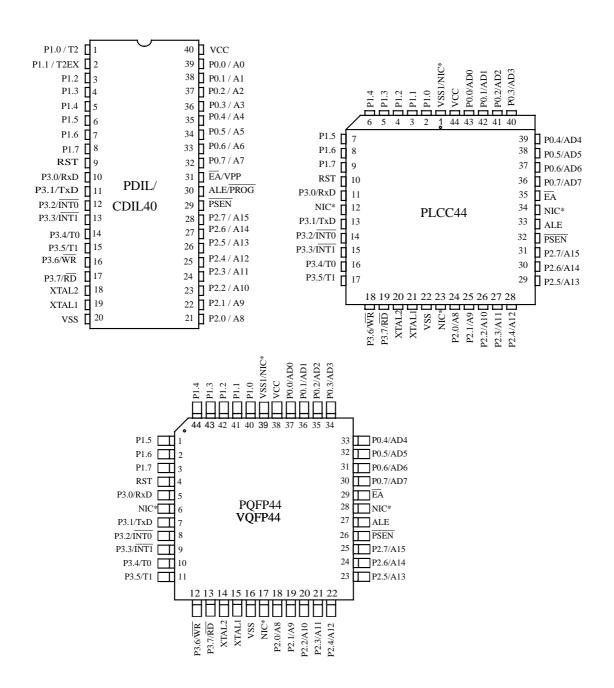
Table 1. All SFRs with their address and their reset value

	Bit address- able		Non Bit addressable									
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F				
F8h									FFh			
F0h	B 0000 0000								F7h			
E8h									EFh			
E0h	ACC 0000 0000								E7h			
D8h									DFh			
D0h	PSW 0000 0000								D7h			
C8h									CFh			
C0h									C7h			
B8h	IP XXX0 0000	SADEN 0000 0000							BFh			
B0h	P3 1111 1111							IPH XXX0 0000	B7h			
A8h	IE 0XX0 0000	SADDR 0000 0000							AFh			
A0h	P2 1111 1111		AUXR1 XXXX XXX0						A7h			
98h	SCON 0000 0000	SBUF XXXX XXXX							9Fh			
90h	P1 1111 1111								97h			
88h	TCON 0000 0000	TMOD 0000 0000	TL0 0000 0000	TL1 0000 0000	TH0 0000 0000	TH1 0000 0000		CKCON XXXX XXX0	8Fh			
80h	P0 1111 1111	SP 0000 0111	DPL 0000 0000	DPH 0000 0000				PCON 00X1 0000	87h			
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F				

reserved



5. Pin Configuration



*NIC: No Internal Connection



Table 2. Pin Description for 40/44 pin packages

NAME AND FUNCTION		PIN NUMBER				scription for 40/44 pin packages			
VSS 20 22 16 1 Ground: OV reference	INEMONIC -				TYPE	NAME AND FUNCTION			
Voc					_				
VCC 40 44 38 1		20							
PO.D-PO.7 39-32 43-36 37-30 IO Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins written to them float and can be used as high impedance inputs. Port be polarized to Vcc or Vss in order to prevent any parasitic current to Port 0 is also the multiplexed low-order address and data bus during external program and data memory. In this application, it uses strongull-up when emitting 1s. P1.0-P1.7 1-8 2-9 40-44 1-3 Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-pus that have 1s written to them are pulled high by the internal pull-pins that have 1s written to them are pulled high by the internal pull-pins that have 1s written to them are pulled high byte to make a surrect current because of the internal pull-ups. P2.0-P2.7 21-28 24-31 18-25 I/O Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-pins that have 1s written to them are pulled high byte the internal pull-pins that have 1s written to them are pulled high byte the internal pull-pins that have 1s written to them are pulled high byte the internal pull-pins that have 1s written to them are pulled high byte during fetches from external program memory and during access to external that use 8-bit addresses (MOVX @RI), port 2 emits the contents of the such as a strong internal pull-ups emitting 1s. During accesses to external that uses 8-bit addresses (MOVX @RI), port 2 emits the contents of the such as a strong internal pull-ups. Port 3 glos over external pull-ups. Port 3 glos over features of the 80C51 family, as listed below. RXD (P3-1): Serial input port IXTO (ss1		1	39	1	- v			
Written to them float and can be used as high impedance inputs. Port be polarized to Vcc or Vss in order to prevent any parasitic current to Port 0 is also the multiplexed low-order address and data bus duri external program and data memory. In this application, it uses stropull-up when emitting 1s. P1.0-P1.7		40	44	38	I	down operation			
P2.0-P2.7 21-28 24-31 18-25 I/O Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pulpins that have 1s written to them are pulled high by the internal pulpins that have 1s written to them are pulled high by the internal pulpins that have 1s written to them are pulled high by the internal pulpins that have 1s written to them are pulled high by the internal pulpins that have 1s written to them are pulled high by the internal pulpins that have 1s written to them are pulled high by the internal pulpins that have 1s written to them are pulled high by the internal pulpins that have 1s written to them are pulled high by the internal pulpins that by the pins that are externally pulpins that by the pins that are externally pulpins that biddresses (MOVX @DPTR). In this and that use 8-bit addresses (MOVX @DPTR). In this and that use 8-bit addresses (MOVX @Ri), port 2 emits the contents of P3.0-P3.7 Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pulpins that have 1s written to them are pulled high by the internal pulpins that have 1s written to them are pulled high by the internal pulpins that by the pins that have 1s written to them are pulled high by the internal pull-ups. Port 3: Por).0-P0.7	39-32	43-36	37-30	I/O	Port 0 : Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs. Port 0 pins must be polarized to Vcc or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s.			
pins that have 1s written to them are pulled high by the internal pusource current because of the internal pull-ups. Port 2 pins that are externally pul source current because of the internal pull-ups. Port 2 pins that are externally pul source current because of the internal pull-ups. Port 2 pins that are external pyth during fetches from external program memory and during accessed data memory that use 16-bit addresses (MOVX @DPTR).In this at uses strong internal pull-ups memiting 1s. During accesses to external that use 8-bit addresses (MOVX @Ri), port 2 emits the contents of the author of the service of the internal pull-ups. Port 3 pins that are externally pull-pins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written to them are pulled high by the internal pull-ins that have 1s written 1s on the pull-ins that have 1s written 1s pull-ins that have 1s written 1s and 1s pull-ins that have 1s written 1s and 1s port 3 pins that have 1s written 1s and 1s purl pull-ins that have 1s written 1s and 1s purl pull-ins that have 1s written 1s and 1s purl pull-ins that have 1s written 1s and 1s purl pull-ins that have 1s written 1s and 1s purl pull-ins that have 1s wri	0-P1.7	1-8	2-9		I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups.			
pins that have 1s written to them are pulled high by the internal procure current because of the internal pull-ups. Port 3 pins that are externally pulsource current because of the internal pull-ups. Port 3 also serves features of the 80C51 family, as listed below. 10 11 5 I RXD (P3.0): Serial input port 11 13 7 O TXD (P3.1): Serial output port 12 14 8 I INTO (P3.2): External interrupt 0 13 15 9 I INTI (P3.3): External interrupt 1 14 16 10 I TO (P3.4): Timer 0 external input 15 17 11 I TI (P3.5): Timer 1 external input 16 18 12 O WR (P3.6): External data memory write strobe 17 19 13 O RD (P3.7): External data memory read strobe Reset 9 10 4 I Reset: A high on this pin for two machine cycles while the oscillator resets the device. An internal diffused resistor to V _{SS} permits a pousing only an external capacitor to V _{CC} . ALE 30 33 27 O (I) Address Latch Enable: Output pulse for latching the low byte of during an access to external memory. In normal operation, ALE is constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and for external timing or clocking. Note that one ALE pulse is skipped access to external data memory.	2.0-P2.7	21-28	24-31	18-25	I/O	Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 emits the contents of the P2 SFR.			
11 13 7 O TXD (P3.1): Serial output port	3.0-P3.7	10-17			I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Port 3 also serves the special features of the 80C51 family, as listed below.			
12		10	11	5	I	RXD (P3.0): Serial input port			
13 15 9 I INTI (P3.3): External interrupt 1 14 16 10 I T0 (P3.4): Timer 0 external input 15 17 11 I T1 (P3.5): Timer 1 external input 16 18 12 O WR (P3.6): External data memory write strobe 17 19 13 O RD (P3.7): External data memory read strobe Reset 9 10 4 I Reset: A high on this pin for two machine cycles while the oscillator resets the device. An internal diffused resistor to V _{SS} permits a pousing only an external capacitor to V _{CC} . ALE 30 33 27 O (I) Address Latch Enable: Output pulse for latching the low byte of during an access to external memory. In normal operation, ALE is constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and for external timing or clocking. Note that one ALE pulse is skipped access to external data memory.		11	13	7	О	TXD (P3.1): Serial output port			
14		12	14	8	I	INTO (P3.2): External interrupt 0			
To the first state of 1/6 (1/3 in X2 mode) the oscillator frequency, and for external timing or clocking. Note that one ALE pulse is skipped access to external data memory.		13	15	9	I	INT1 (P3.3): External interrupt 1			
Reset 9 10 4 I Reset: A high on this pin for two machine cycles while the oscillator resets the device. An internal diffused resistor to V _{SS} permits a pousing only an external capacitor to V _{CC} . ALE 30 33 27 O (I) Address Latch Enable: Output pulse for latching the low byte of during an access to external memory. In normal operation, ALE is constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and for external timing or clocking. Note that one ALE pulse is skipped access to external data memory.		14	16	10	I	T0 (P3.4): Timer 0 external input			
Reset 9 10 4 I Reset: A high on this pin for two machine cycles while the oscillator resets the device. An internal diffused resistor to V _{SS} permits a pousing only an external capacitor to V _{CC} . ALE 30 33 27 O (I) Address Latch Enable: Output pulse for latching the low byte of during an access to external memory. In normal operation, ALE is constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and for external timing or clocking. Note that one ALE pulse is skipped access to external data memory.		15	17	11	I	T1 (P3.5): Timer 1 external input			
Reset 9 10 4 I Reset: A high on this pin for two machine cycles while the oscillator resets the device. An internal diffused resistor to V _{SS} permits a pousing only an external capacitor to V _{CC} . ALE 30 33 27 O (I) Address Latch Enable: Output pulse for latching the low byte of during an access to external memory. In normal operation, ALE is constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and for external timing or clocking. Note that one ALE pulse is skipped access to external data memory.		16	18	12	О	WR (P3.6): External data memory write strobe			
resets the device. An internal diffused resistor to V _{SS} permits a pousing only an external capacitor to V _{CC} . ALE 30 33 27 O (I) Address Latch Enable: Output pulse for latching the low byte of during an access to external memory. In normal operation, ALE is constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and for external timing or clocking. Note that one ALE pulse is skipped access to external data memory.		17	19	13	О	RD (P3.7): External data memory read strobe			
during an access to external memory. In normal operation, ALE is constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and for external timing or clocking. Note that one ALE pulse is skipped access to external data memory.	eset	9	10	4	I	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC} .			
DSEN 20 22 26 O Droggon Stone ENghler The good stocks to get all	LE	30	33	27	O (I)	Address Latch Enable: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory.			
executing code from the external program memory, \overline{PSEN} is activate machine cycle, except that two \overline{PSEN} activations are skipped during	SEN	29	32	26	0	Program Store ENable: The read strobe to external program memory. When executing code from the external program memory, \overline{PSEN} is activated twice each machine cycle, except that two \overline{PSEN} activations are skipped during each access to external data memory. \overline{PSEN} is not activated during fetches from internal program memory.			
EA 31 35 29 I External Access Enable: EA must be externally held low to enable to fetch code from external program memory locations.	Ā	31	35	29	I	External Access Enable: \overline{EA} must be externally held low to enable the device to fetch code from external program memory locations.			
XTAL1 19 21 15 I Crystal 1: Input to the inverting oscillator amplifier and input to to clock generator circuits.	TAL1	19	21	15	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.			
XTAL2 18 20 14 O Crystal 2: Output from the inverting oscillator amplifier	TAL2	18	20	14	О				



6. TS80C31X2 Enhanced Features

In comparison to the original 80C31, the TS80C31X2 implements some new features, which are:

- The X2 option.
- The Dual Data Pointer.
- The 4 level interrupt priority system.
- · The power-off flag.
- The ONCE mode.
- Enhanced UART

6.1 X2 Feature

The TS80C31X2 core needs only 6 clock periods per machine cycle. This feature called "X2" provides the following advantages:

- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power.
- Save power consumption while keeping same CPU power (oscillator power saving).
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes.
- Increase CPU power by 2 while keeping same crystal frequency.

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

6.1.1 Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 1. shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 2. shows the mode switching waveforms.

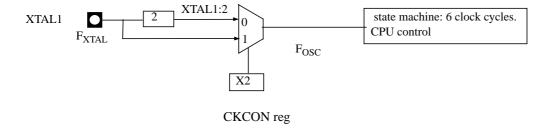


Figure 1. Clock Generation Diagram



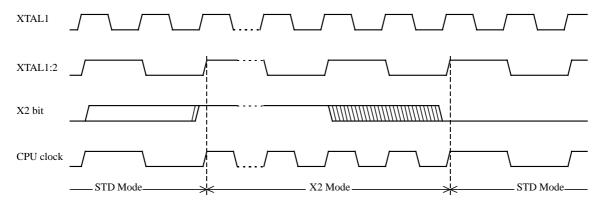


Figure 2. Mode Switching Waveforms

The X2 bit in the CKCON register (See Table 3.) allows to switch from 12 clock cycles per instruction to 6 clock cycles and vice versa. At reset, the standard speed is activated (STD mode). Setting this bit activates the X2 feature (X2 mode).

CAUTION

In order to prevent any incorrect operation while operating in X2 mode, user must be aware that all peripherals using clock frequency as time reference (UART, timers) will have their time reference divided by two. For example a free running timer generating an interrupt every 20 ms will then generate an interrupt every 10 ms. UART with 4800 baud rate will have 9600 baud rate.



Table 3. CKCON Register

CKCON - Clock Control Register (8Fh)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	X2

Bit Number	Bit Mnemonic	Description					
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.					
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.					
5	-	The value read from this bit is indeterminate. Do not set this bit.					
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.					
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.					
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.					
1	-	Reserved The value read from this bit is indeterminate. Do not set this bit.					
0	X2	CPU and peripheral clock bit Clear to select 12 clock periods per machine cycle (STD mode, F _{OSC} =F _{XTAL} /2). Set to select 6 clock periods per machine cycle (X2 mode, F _{OSC} =F _{XTAL}).					

Reset Value = XXXX XXX0b

Not bit addressable

For further details on the X2 feature, please refer to ANM072 available on the web (http://www.atmel-wm.com)



6.2 Dual Data Pointer Register Ddptr

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 (See Table 5.) that allows the program code to switch between them (Refer to Figure 3).

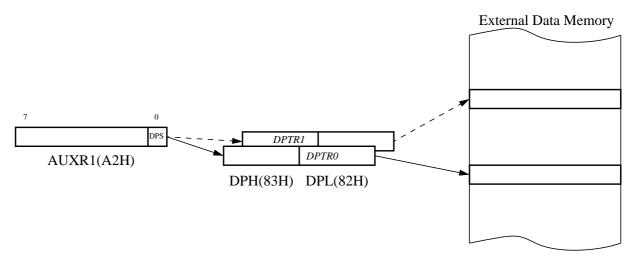


Figure 3. Use of Dual Pointer



Table 4. AUXR1: Auxiliary Register 1

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	DPS

Bit Number	Bit Mnemonic	Description
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
1	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
0	DPS	Data Pointer Selection Clear to select DPTR0. Set to select DPTR1.

Reset Value = XXXX XXX0

Not bit addressable

Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.



ASSEMBLY LANGUAGE

```
; Block move using dual data pointers
; Destroys DPTR0, DPTR1, A and PSW
; note: DPS exits opposite of entry state
; unless an extra INC AUXR1 is added
00A2
           AUXR1 EQU 0A2H
0000 909000MOV DPTR,#SOURCE
                                      ; address of SOURCE
0003 05A2 INC AUXR1
                                      ; switch data pointers
0005 90A000 MOV DPTR,#DEST
                                      ; address of DEST
0008
          LOOP:
0008 05A2 INC AUXR1
                                      ; switch data pointers
                                      ; get a byte from SOURCE
000A E0
          MOVX A, @DPTR
          INC DPTR
                                      ; increment SOURCE address
000B A3
                                      ; switch data pointers
000C 05A2 INC AUXR1
000E F0
          MOVX @DPTR,A
                                      ; write the byte to DEST
000F A3
           INC DPTR
                                      ; increment DEST address
0010 70F6 JNZ LOOP
                                      ; check for 0 terminator
0012 05A2 INC AUXR1
                                      ; (optional) restore DPS
```

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.

Rev. C - 15 January, 2001



6.3 TS80C31X2 Serial I/O Port

The serial I/O port in the TS80C31X2 is compatible with the serial I/O port in the 80C31.

It provides both synchronous and asynchronous communication modes. It operates as an Universal Asynchronous Receiver and Transmitter (UART) in three full-duplex modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simultaneously and at different baud rates

Serial I/O port includes the following enhancements:

- Framing error detection
- Automatic address recognition

6.3.1 Framing Error Detection

Framing bit error detection is provided for the three asynchronous modes (modes 1, 2 and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON register (See Figure 4).

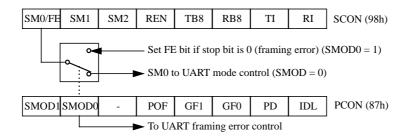


Figure 4. Framing Error Block Diagram

When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See Table 5.) bit is set.



Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 5. and Figure 6.).

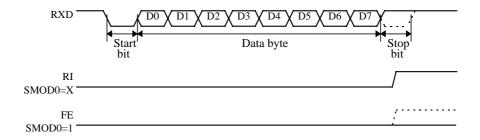


Figure 5. UART Timings in Mode 1

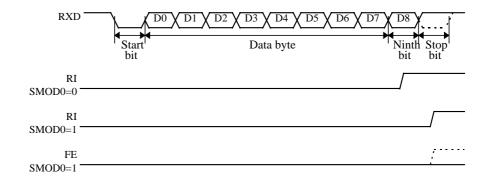


Figure 6. UART Timings in Modes 2 and 3

6.3.2 Automatic Address Recognition

The automatic address recognition feature is enabled when the multiprocessor communication feature is enabled (SM2 bit in SCON register is set).

Implemented in hardware, automatic address recognition enhances the multiprocessor communication feature by allowing the serial port to examine the address of each incoming command frame. Only when the serial port recognizes its own address, the receiver sets RI bit in SCON register to generate an interrupt. This ensures that the CPU is not interrupted by command frames addressed to other devices.

If desired, you may enable the automatic address recognition feature in mode 1. In this configuration, the stop bit takes the place of the ninth data bit. Bit RI is set only when the received command frame address matches the device's address and is terminated by a valid stop bit.

To support automatic address recognition, a device is identified by a given address and a broadcast address.

NOTE: The multiprocessor communication and automatic address recognition features cannot be enabled in mode 0 (i.e. setting SM2 bit in SCON register in mode 0 has no effect).

Rev. C - 15 January, 2001



6.3.3 Given Address

Each device has an individual address that is specified in SADDR register; the SADEN register is a mask byte that contains don't-care bits (defined by zeros) to form the device's given address. The don't-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed. To address a device by its individual address, the SADEN mask byte must be 1111 1111b. For example:

SADDR	0101 0110b
SADEN	1111 1100b
Given	0101 01XXb

The following is an example of how to use given addresses to address different slaves:

Slave A:	SADDR <u>SADEN</u> Given	1111 0001b 1111 1010b 1111 0X0Xb
Slave B:	SADDR <u>SADEN</u> Given	1111 0011b 1111 1001b 1111 0XX1b
Slave C:	SADDR <u>SADEN</u> Given	1111 0010b 1111 1101b 1111 00X1b

The SADEN byte is selected so that each slave may be addressed separately.

For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g. 1111 0000b).

For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. 1111 0011b).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

6.3.4 Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

SADDR	0101 0110b
SADEN	1111 1100b
Broadcast = SADDR OR SADEN	1111 111Xb

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

		C
Slave A:	SADDR <u>SADEN</u> Broadcast	1111 0001b 1111 1010b 1111 1X11b,
Slave B:	SADDR <u>SADEN</u> Broadcast	1111 0011b 1111 1001b 1111 1X11B,
Slave C:	SADDR= <u>SADEN</u> Broadcast	1111 0010b 1111 1101b 1111 1111b

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send and address FBh.



6.3.5 Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are XXXX XXXXb (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

SADEN - Slave Address Mask Register (B9h)

7	6	5	4	3	2	1	0

 $Reset\ Value=0000\ 0000b$

Not bit addressable

SADDR - Slave Address Register (A9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b

Not bit addressable



Table 5. SCON Register

SCON - Serial Control Register (98h)

7	6	5	4	3	2	1	0
FE/SM0	SM1	SM2	REN	TB8	RB8	TI	RI

Bit Number	Bit Mnemonic	Description					
7	FE	Framing Error bit (SMOD0=1) Clear to reset the error state, not cleared by a valid stop bit. Set by hardware when an invalid stop bit is detected. SMOD0 must be set to enable access to the FE bit					
	SM0	Serial port Mode bit 0 Refer to SM1 for serial port mode selection. SMOD0 must be cleared to enable access to the SM0 bit					
		Serial port Mode bit 1 SM0 SM1 Mode Description Baud Rate					
6	SM1	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	ode)				
5	SM2	Serial port Mode 2 bit / Multiprocessor Communication Enable bit Clear to disable multiprocessor communication feature. Set to enable multiprocessor communication feature in mode 2 and 3, and eventually mode 1. This bit should be cleared in mode 0.					
4	REN	Reception Enable bit Clear to disable serial reception. Set to enable serial reception.					
3	ТВ8	Transmitter Bit 8 / Ninth bit to transmit in modes 2 and 3. Clear to transmit a logic 0 in the 9th bit. Set to transmit a logic 1 in the 9th bit.					
2	RB8	Receiver Bit 8 / Ninth bit received in modes 2 and 3 Cleared by hardware if 9th bit received is a logic 0. Set by hardware if 9th bit received is a logic 1. In mode 1, if SM2 = 0, RB8 is the received stop bit. In mode 0 RB8 is not used.					
1	TI	Transmit Interrupt flag Clear to acknowledge interrupt. Set by hardware at the end of the 8th bit time in mode 0 or at the beginning of the stop bit in the other modes.					
0	RI	Receive Interrupt flag Clear to acknowledge interrupt. Set by hardware at the end of the 8th bit time in mode 0, see Figure 5. and Figure 6. in the other modes.					

Reset Value = 0000 0000b

Bit addressable



Table 6. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0
SMOD1	SMOD0	-	POF	GF1	GF0	PD	IDL

Bit Number	Bit Mnemonic	Description
7	SMOD1	Serial port Mode bit 1 Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	Serial port Mode bit 0 Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	POF	Power-Off Flag Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	Power-Down mode bit Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	Idle mode bit Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b

Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.



6.4 Interrupt System

The TS80C31X2 has a total of 5 interrupt vectors: two external interrupts (INTO and INTI), two timer interrupts (timers 0 and 1) and the serial port interrupt. These interrupts are shown in Figure 7.

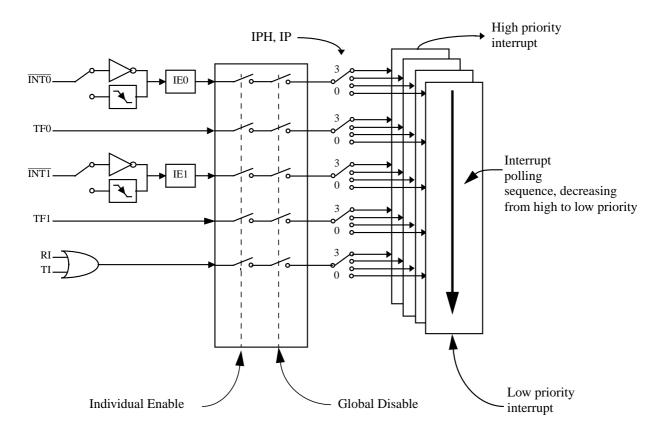


Figure 7. Interrupt Control System

Each of the interrupt sources can be individually enabled or disabled by setting or clearing a bit in the Interrupt Enable register (See Table 8.). This register also contains a global disable bit, which must be cleared to disable all interrupts at once.

Each interrupt source can also be individually programmed to one out of four priority levels by setting or clearing a bit in the Interrupt Priority register (See Table 9.) and in the Interrupt Priority High register (See Table 10.). shows the bit values and priority levels associated with each combination.



Table 7. Priority Level Bit Values

IPH.x	IP.x	Interrupt Level Priority
0	0	0 (Lowest)
0	1	1
1	0	2
1	1	3 (Highest)

A low-priority interrupt can be interrupted by a high priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

If two interrupt requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If interrupt requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence.

Table 8. IE Register

IE - Interrupt Enable Register (A8h)

7	6	5	4	3	2	1	0
EA	-	-	ES	ET1	EX1	ET0	EX0

Bit Number	Bit Mnemonic	Description
7	EA	Enable All interrupt bit Clear to disable all interrupts. Set to enable all interrupts. If EA=1, each interrupt source is individually enabled or disabled by setting or clearing its own interrupt enable bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	ES	Serial port Enable bit Clear to disable serial port interrupt. Set to enable serial port interrupt.
3	ET1	Timer 1 overflow interrupt Enable bit Clear to disable timer 1 overflow interrupt. Set to enable timer 1 overflow interrupt.
2	EX1	External interrupt 1 Enable bit Clear to disable external interrupt 1. Set to enable external interrupt 1.
1	ET0	Timer 0 overflow interrupt Enable bit Clear to disable timer 0 overflow interrupt. Set to enable timer 0 overflow interrupt.
0	EX0	External interrupt 0 Enable bit Clear to disable external interrupt 0. Set to enable external interrupt 0.

Reset Value = 0XX0 0000b

Bit addressable

Table 9. IP Register



IP - Interrupt Priority Register (B8h)

7	6	5	4	3	2	1	0
-	-	-	PS	PT1	PX1	PT0	PX0

Bit Number	Bit Mnemonic	Description
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	PS	Serial port Priority bit Refer to PSH for priority level.
3	PT1	Timer 1 overflow interrupt Priority bit Refer to PT1H for priority level.
2	PX1	External interrupt 1 Priority bit Refer to PX1H for priority level.
1	PT0	Timer 0 overflow interrupt Priority bit Refer to PT0H for priority level.
0	PX0	External interrupt 0 Priority bit Refer to PX0H for priority level.

Reset Value = XXX0 0000b

Bit addressable



Table 10. IPH Register

IPH - Interrupt Priority High Register (B7h)

7	6	5	4	3	2	1	0
-	-	-	PSH	PT1H	PX1H	РТ0Н	PX0H

Bit Number	Bit Mnemonic	Description					
7	-	Reserved The value read fr	Reserved The value read from this bit is indeterminate. Do not set this bit.				
6	-	Reserved The value read fr	rom this bit is i	ndeterminate. Do not set this bit.			
5	-	Reserved The value read fr	rom this bit is i	ndeterminate. Do not set this bit.			
4	PSH	Serial port Priority PSH 0 0 1	High bit PS 0 1 0 1	Priority Level Lowest Highest			
3	PT1H	Timer 1 overflow in	terrupt Priori	ty High bit Priority Level Lowest Highest			
2	PX1H	External interrupt 1	Priority High PX1 0 1 0 1 1	Priority Level Lowest Highest			
1	РТОН	Timer 0 overflow in	terrupt Priori	ty High bit Priority Level Lowest Highest			
0	РХ0Н	External interrupt (PX0H 0 0 1 1	Priority High	Priority Level Lowest Highest			

Reset Value = XXX0 0000b

Not bit addressable



6.5 Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely: the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give and indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The over way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

6.6 Power-Down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 6., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{\text{INT0}}$ and $\overline{\text{INT1}}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.

Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 8. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.

Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C31X2 into power-down mode.

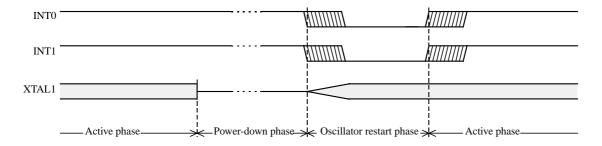


Figure 8. Power-Down Exit Waveform

Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does no affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

NOTE: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.



Table 11. The state of ports during idle and power-down modes

Mode	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power Down	External	0	0	Floating	Port Data	Port Data	Port Data



6.7 ONCETM Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS80C31X2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C31X2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and PSEN is high.
- Hold ALE low as RST is deactivated.

While the TS80C31X2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 26. shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

Table 12. External Pin Status during ONCE Mode

ALE	PSEN	PSEN Port 0		Port 2	Port 3	XTAL1/2
Weak pull-up	Weak pull-up	Float	Weak pull-up	Weak pull-up	Weak pull-up	Active



6.8 Power-Off Flag

The power-off flag allows the user to distinguish between a "cold start" reset and a "warm start" reset.

A cold start reset is the one induced by V_{CC} switch-on. A warm start reset occurs while V_{CC} is still applied to the device and could be generated for example by an exit from power-down.

The power-off flag (POF) is located in PCON register (See Table 13.). POF is set by hardware when V_{CC} rises from 0 to its nominal voltage. The POF can be set or cleared by software allowing the user to determine the type of reset.

The POF value is only relevant with a Vcc range from 4.5V to 5.5V. For lower Vcc value, reading POF bit will return indeterminate value.

Table 13. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0	
SMOD1	SMOD0	-	POF	GF1	GF0	PD	IDL	

Bit Number	Bit Mnemonic	Description
7	SMOD1	Serial port Mode bit 1 Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	Serial port Mode bit 0 Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	POF	Power-Off Flag Clear to recognize next reset type. Set by hardware when V_{CC} rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	Power-Down mode bit Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	Idle mode bit Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b

Not bit addressable



7. Electrical Characteristics

7.1 Absolute Maximum Ratings (1)

Ambiant Temperature Under Bias:

C = commercial0°C to 70°C I = industrial-40°C to 85°C Storage Temperature -65° C to $+ 150^{\circ}$ C Voltage on V_{CC} to V_{SS} -0.5 V to + 7 VVoltage on V_{PP} to V_{SS} -0.5 V to + 13 VVoltage on Any Pin to VSS -0.5 V to $V_{CC} + 0.5 \text{ V}$

 $1 W^{(2)}$ Power Dissipation

NOTES

7.2 Power consumption measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel Wireless & Microcontrollers new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel Wireless & Microcontrollers presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

^{1.} Stresses at or above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

This value is based on the maximum allowable die temperature and the thermal resistance of the package.



7.3 DC Parameters for Standard Voltage

Ta = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz. Ta = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

Table 14. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3 ⁽⁶⁾			0.3 0.45 1.0	V V V	$I_{OL} = 100 \ \mu A^{(4)}$ $I_{OL} = 1.6 \ mA^{(4)}$ $I_{OL} = 3.5 \ mA^{(4)}$
V _{OL1}	Output Low Voltage, port 0 (6)			0.3 0.45 1.0	V V V	$I_{OL} = 200 \ \mu A^{(4)}$ $I_{OL} = 3.2 \ mA^{(4)}$ $I_{OL} = 7.0 \ mA^{(4)}$
V _{OL2}	Output Low Voltage, ALE, PSEN			0.3 0.45 1.0	V V V	$I_{OL} = 100 \ \mu A^{(4)}$ $I_{OL} = 1.6 \ mA^{(4)}$ $I_{OL} = 3.5 \ mA^{(4)}$
V _{OH}	Output High Voltage, ports 1, 2, 3	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	$\begin{split} I_{OH} &= -10 \ \mu A \\ I_{OH} &= -30 \ \mu A \\ I_{OH} &= -60 \ \mu A \\ V_{CC} &= 5 \ V \pm 10\% \end{split}$
V _{OH1}	Output High Voltage, port 0	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	$I_{OH} = -200 \ \mu A$ $I_{OH} = -3.2 \ mA$ $I_{OH} = -7.0 \ mA$ $V_{CC} = 5 \ V \pm 10\%$
V _{OH2}	Output High Voltage, ALE, PSEN	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	$I_{OH} = -100 \ \mu A$ $I_{OH} = -1.6 \ mA$ $I_{OH} = -3.5 \ mA$ $V_{CC} = 5 \ V \pm 10\%$
R _{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
I _{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	μА	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	μΑ	0.45 V < Vin < V _{CC}
I _{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	μΑ	Vin = 2.0 V
C _{IO}	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I_{PD}	Power Down Current		20 (5)	50	μА	$2.0 \text{ V} < \text{V}_{\text{CC}} < 5.5 \text{ V}^{(3)}$
I _{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.4 Freq (MHz) @12MHz 5.8 @16MHz 7.4	mA	$V_{CC} = 5.5 V^{(1)}$



Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
I _{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			3 + 0.6 Freq (MHz) @12MHz 10.2 @16MHz 12.6	mA	$V_{CC} = 5.5 V^{(8)}$
I _{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.25+0.3 Freq (MHz) @12MHz 3.9 @16MHz 5.1	mA	$V_{CC} = 5.5 V^{(2)}$

7.4 DC Parameters for Low Voltage

28

TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz. TA = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.

Table 15. DC Parameters for Low Voltage

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3 (6)			0.45	V	$I_{OL} = 0.8 \text{ mA}^{(4)}$
V _{OL1}	Output Low Voltage, port 0, ALE, PSEN (6)			0.45	V	$I_{OL} = 1.6 \text{ mA}^{(4)}$
V _{OH}	Output High Voltage, ports 1, 2, 3	0.9 V _{CC}			V	$I_{OH} = -10 \mu A$
V _{OH1}	Output High Voltage, port 0, ALE, PSEN	0.9 V _{CC}			V	$I_{OH} = -40 \mu A$
I _{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	μА	Vin = 0.45 V
I _{LI}	Input Leakage Current			±10	μА	0.45 V < Vin < V _{CC}
I _{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	μА	Vin = 2.0 V
R _{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I _{PD}	Power Down Current		20 ⁽⁵⁾ 10 ⁽⁵⁾	50 30	μА	$V_{CC} = 2.0 \text{ V to } 5.5 \text{ V}^{(3)}$ $V_{CC} = 2.0 \text{ V to } 3.3 \text{ V}^{(3)}$
I _{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) @12MHz 3.4 @16MHz 4.2	mA	$V_{CC} = 3.3 V^{(1)}$
I _{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) @12MHz 4.6 @16MHz 5.8	mA	$V_{CC} = 3.3 V^{(8)}$



Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
I _{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.15 Freq (MHz) + 0.2 @12MHz 2 @16MHz 2.6	mA	$V_{CC} = 3.3 V^{(2)}$

NOTES

- 1. I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5$ ns (see Figure 13.), $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} 0.5$ V; XTAL2 N.C.; $\overline{EA} = RST = Port\ 0 = V_{CC}$. I_{CC} would be slightly higher if a crystal oscillator used..
- 2. Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5$ ns, $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} 0.5$ V; XTAL2 N.C; Port $0 = V_{CC}$; $\overline{EA} = RST = V_{SS}$ (see Figure 11.).
- 3. Power Down I_{CC} is measured with all output pins disconnected; $\overline{EA} = V_{SS}$, PORT $0 = V_{CC}$; XTAL2 NC.; RST = V_{SS} (see Figure 12.).
- 4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the $V_{OL}s$ of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.
- 5. Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
 - Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:

Maximum I_{OL} per port pin: 10 mA

Maximum I_{OL} per 8-bit port:

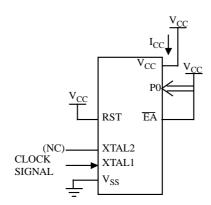
Port 0: 26 mA

Ports 1, 2 and 3: 15 mA

Maximum total I_{OL} for all output pins: 71 mA

 $If I_{OL}\ exceeds\ the\ test\ condition,\ V_{OL}\ may\ exceed\ the\ related\ specification.\ Pins\ are\ not\ guaranteed\ to\ sink\ current\ greater\ than\ the\ listed\ test\ conditions.$

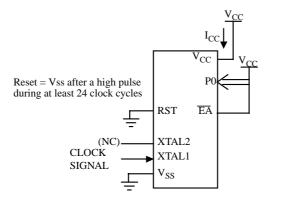
- 7. For other values, please contact your sales office.
- 8. Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5$ ns (see Figure 13.), $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} 0.5$ V; XTAL2 N.C.; $\overline{EA} = Port\ 0 = V_{CC}$; RST = V_{SS} . The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.



All other pins are disconnected.

Figure 9. I_{CC} Test Condition, under reset





All other pins are disconnected.

Figure 10. Operating I_{CC} Test Condition

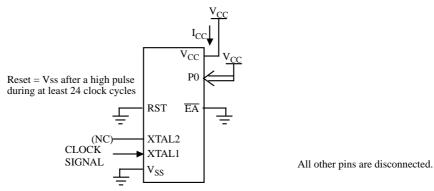


Figure 11. I_{CC} Test Condition, Idle Mode

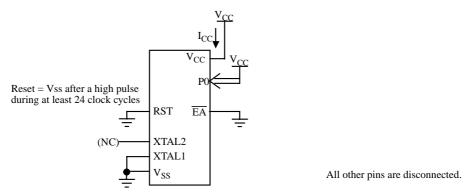


Figure 12. I_{CC} Test Condition, Power-Down Mode

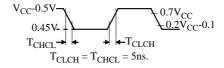


Figure 13. Clock Signal Waveform for $I_{\hbox{\scriptsize CC}}$ Tests in Active and Idle Modes



7.5 AC Parameters

7.5.1 Explanation of the AC Symbols

Each timing symbol has 5 characters. The first character is always a "T" (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example: T_{AVLL} = Time for Address Valid to ALE Low.

 T_{LLPL} = Time for ALE Low to \overline{PSEN} Low.

TA = 0 to +70°C (commercial temperature range); $V_{SS} = 0$ V; $V_{CC} = 5$ V \pm 10%; -M and -V ranges.

TA = -40°C to +85°C (industrial temperature range); $V_{SS} = 0$ V; $V_{CC} = 5$ V \pm 10%; -M and -V ranges.

TA = 0 to +70°C (commercial temperature range); $V_{SS} = 0$ V; 2.7 V < $V_{CC} < 5.5$ V; -L range.

TA = -40°C to +85°C (industrial temperature range); $V_{SS} = 0~V; 2.7~V < V_{CC} < 5.5~V;$ -L range.

Table 16. gives the maximum applicable load capacitance for Port 0, Port 1, 2 and 3, and ALE and $\overline{\text{PSEN}}$ signals. Timings will be guaranteed if these capacitances are respected. Higher capacitance values can be used, but timings will then be degraded.

 Port 0
 100
 50
 100

 Port 1, 2, 3
 80
 50
 80

 ALE / PSEN
 100
 30
 100

Table 16. Load Capacitance versus speed range, in pF

Table 18., Table 21. and Table 24. give the description of each AC symbols.

Table 19., Table 22. and Table 25. give for each range the AC parameter.

Table 20., Table 23. and Table 26. give the frequency derating formula of the AC parameter. To calculate each AC symbols, take the x value corresponding to the speed grade you need (-M, -V or -L) and replace this value in the formula. Values of the frequency must be limited to the corresponding speed grade:

Table 17. Max frequency for derating formula regarding the speed grade

	-M X1 mode	-M X2 mode	-V X1 mode	-V X2 mode	-L X1 mode	-L X2 mode
Freq (MHz)	40	20	40	30	30	20
T (ns)	25	50	25	33.3	33.3	50

Example:

 T_{LLIV} in X2 mode for a -V part at 20 MHz (T = $1/20^{E6}$ = 50 ns):

x= 25 (Table 20.)

T=50ns

 $T_{LLIV} = 2T - x = 2 \times 50 - 25 = 75 \text{ns}$



7.5.2 External Program Memory Characteristics

Table 18. Symbol Description

Symbol	Parameter
T	Oscillator clock period
T _{LHLL}	ALE pulse width
T _{AVLL}	Address Valid to ALE
T _{LLAX}	Address Hold After ALE
T _{LLIV}	ALE to Valid Instruction In
T _{LLPL}	ALE to PSEN
T_{PLPH}	PSEN Pulse Width
T _{PLIV}	PSEN to Valid Instruction In
T _{PXIX}	Input Instruction Hold After PSEN
T _{PXIZ}	Input Instruction FloatAfter PSEN
T _{PXAV}	PSEN to Address Valid
T _{AVIV}	Address to Valid Instruction In
T_{PLAZ}	PSEN Low to Address Float

Table 19. AC Parameters for Fix Clock

Speed		M MHz	X2 r 30 N	V node MHz z equiv.	-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		de X2 mode standard mode 20 MHz 30 MHz		rd mode	Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
T	25		33		25		50		33		ns	
$T_{ m LHLL}$	40		25		42		35		52		ns	
T _{AVLL}	10		4		12		5		13		ns	
T _{LLAX}	10		4		12		5		13		ns	
T _{LLIV}		70		45		78		65		98	ns	
T_{LLPL}	15		9		17		10		18		ns	
T_{PLPH}	55		35		60		50		75		ns	
T _{PLIV}		35		25		50		30		55	ns	
T _{PXIX}	0		0		0		0		0		ns	
T _{PXIZ}		18		12		20		10		18	ns	
T _{AVIV}		85		53		95		80		122	ns	
T_{PLAZ}		10		10		10		10		10	ns	



Symbol	Туре	Standard Clock	X2 Clock	-M	-V	-L	Units
T _{LHLL}	Min	2 T - x	T - x	10	8	15	ns
T _{AVLL}	Min	T - x	0.5 T - x	15	13	20	ns
T _{LLAX}	Min	T - x	0.5 T - x	15	13	20	ns
T _{LLIV}	Max	4 T - x	2 T - x	30	22	35	ns
T_{LLPL}	Min	T - x	0.5 T - x	10	8	15	ns
T_{PLPH}	Min	3 T - x	1.5 T - x	20	15	25	ns
T _{PLIV}	Max	3 T - x	1.5 T - x	40	25	45	ns
T _{PXIX}	Min	x	х	0	0	0	ns
T _{PXIZ}	Max	T - x	0.5 T - x	7	5	15	ns
T _{AVIV}	Max	5 T - x	2.5 T - x	40	30	45	ns
T _{PLAZ}	Max	X	Х	10	10	10	ns

7.5.3 External Program Memory Read Cycle

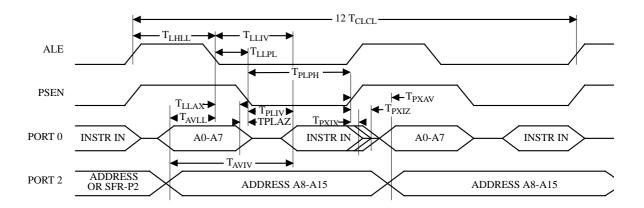


Figure 14. External Program Memory Read Cycle



7.5.4 External Data Memory Characteristics

Table 21. Symbol Description

Symbol	Parameter
T _{RLRH}	RD Pulse Width
T _{WLWH}	WR Pulse Width
T _{RLDV}	RD to Valid Data In
T _{RHDX}	Data Hold After RD
T _{RHDZ}	Data Float After RD
T _{LLDV}	ALE to Valid Data In
T _{AVDV}	Address to Valid Data In
T _{LLWL}	ALE to WR or RD
T _{AVWL}	Address to WR or RD
T _{QVWX}	Data Valid to WR Transition
T _{QVWH}	Data set-up to WR High
T _{WHQX}	Data Hold After WR
T _{RLAZ}	RD Low to Address Float
T _{WHLH}	RD or WR High to ALE high



Table 22. AC Parameters for a Fix Clock

Speed		M MHz	X2 r 30 N	V node MHz z equiv.	standar	V rd mode MHz	X2 r 20 N	L mode MHz z equiv.	standaı	L rd mode MHz	Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T _{RLRH}	130		85		135		125		175		ns
T_{WLWH}	130		85		135		125		175		ns
T_{RLDV}		100		60		102		95		137	ns
T_{RHDX}	0		0		0		0		0		ns
T_{RHDZ}		30		18		35		25		42	ns
T_{LLDV}		160		98		165		155		222	ns
T _{AVDV}		165		100		175		160		235	ns
T_{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T _{AVWL}	75		47		80		70		103		ns
T _{QVWX}	10		7		15		5		13		ns
T _{QVWH}	160		107		165		155		213		ns
T_{WHQX}	15		9		17		10		18		ns
T_{RLAZ}		0		0		0		0		0	ns
T_{WHLH}	10	40	7	27	15	35	5	45	13	53	ns



Table 23. AC Parameters for a Variable Clock: derating formula

Symbol	Туре	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{RLRH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{WLWH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{RLDV}	Max	5 T - x	2.5 T - x	25	23	30	ns
T_{RHDX}	Min	x	х	0	0	0	ns
T_{RHDZ}	Max	2 T - x	T - x	20	15	25	ns
T_{LLDV}	Max	8 T - x	4T -x	40	35	45	ns
T _{AVDV}	Max	9 T - x	4.5 T - x	60	50	65	ns
T_{LLWL}	Min	3 T - x	1.5 T - x	25	20	30	ns
T_{LLWL}	Max	3 T + x	1.5 T + x	25	20	30	ns
T_{AVWL}	Min	4 T - x	2 T - x	25	20	30	ns
T_{QVWX}	Min	T - x	0.5 T - x	15	10	20	ns
T_{QVWH}	Min	7 T - x	3.5 T - x	15	10	20	ns
T_{WHQX}	Min	T - x	0.5 T - x	10	8	15	ns
T_{RLAZ}	Max	x	х	0	0	0	ns
T_{WHLH}	Min	T - x	0.5 T - x	15	10	20	ns
T_{WHLH}	Max	T + x	0.5 T + x	15	10	20	ns

7.5.5 External Data Memory Write Cycle

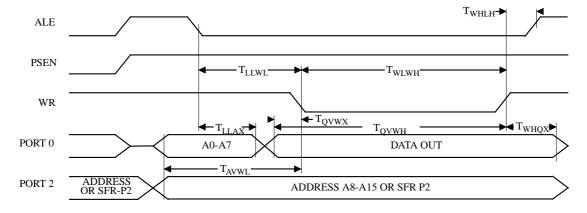


Figure 15. External Data Memory Write Cycle



7.5.6 External Data Memory Read Cycle

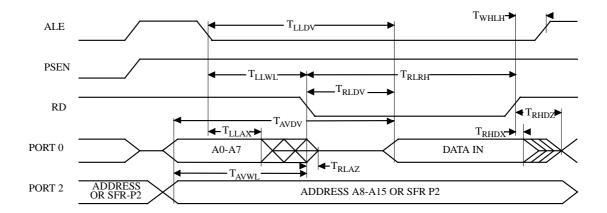


Figure 16. External Data Memory Read Cycle

7.5.7 Serial Port Timing - Shift Register Mode

Table 24. Symbol Description

Symbol	Parameter
T _{XLXL}	Serial port clock cycle time
T _{QVHX}	Output data set-up to clock rising edge
T _{XHQX}	Output data hold after clock rising edge
T _{XHDX}	Input data hold after clock rising edge
T _{XHDV}	Clock rising edge to input data valid

Table 25. AC Parameters for a Fix Clock

Speed		M MHz	X2 n 30 N	V node MHz z equiv.		V rd mode MHz	X2 r 20 N	L node MHz z equiv.	standar	L d mode MHz	Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T _{XLXL}	300		200		300		300		400		ns
T _{QVHX}	200		117		200		200		283		ns
T _{XHQX}	30		13		30		30		47		ns
T _{XHDX}	0		0		0		0		0		ns
T _{XHDV}		117		34		117		117		200	ns



Table 26. AC Parameters for a Variable Clock: derating formula

Symbol	Туре	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{XLXL}	Min	12 T	6 T				ns
T _{QVHX}	Min	10 T - x	5 T - x	50	50	50	ns
T _{XHQX}	Min	2 T - x	T - x	20	20	20	ns
T _{XHDX}	Min	Х	х	0	0	0	ns
T _{XHDV}	Max	10 T - x	5 T- x	133	133	133	ns

7.5.8 Shift Register Timing Waveforms

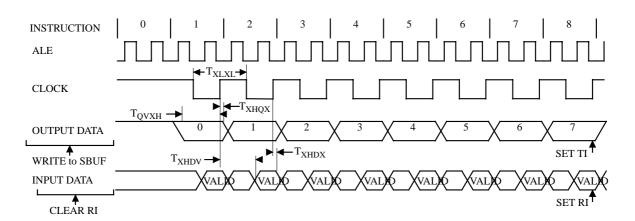


Figure 17. Shift Register Timing Waveforms



7.5.9 External Clock Drive Characteristics (XTAL1)

Table 27. AC Parameters

Symbol	Parameter	Min	Max	Units
T _{CLCL}	Oscillator Period	25		ns
T _{CHCX}	High Time	5		ns
T _{CLCX}	Low Time	5		ns
T _{CLCH}	Rise Time		5	ns
T _{CHCL}	Fall Time		5	ns
T _{CHCX} /T _{CLCX}	Cyclic ratio in X2 mode	40	60	%

7.5.10 External Clock Drive Waveforms

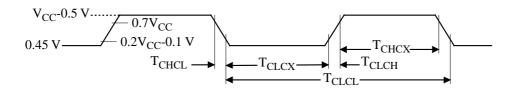


Figure 18. External Clock Drive Waveforms

7.5.11 AC Testing Input/Output Waveforms



Figure 19. AC Testing Input/Output Waveforms

AC inputs during testing are driven at V_{CC} - 0.5 for a logic "1" and 0.45V for a logic "0". Timing measurement are made at V_{IH} min for a logic "1" and V_{IL} max for a logic "0".

7.5.12 Float Waveforms

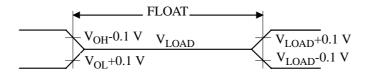


Figure 20. Float Waveforms

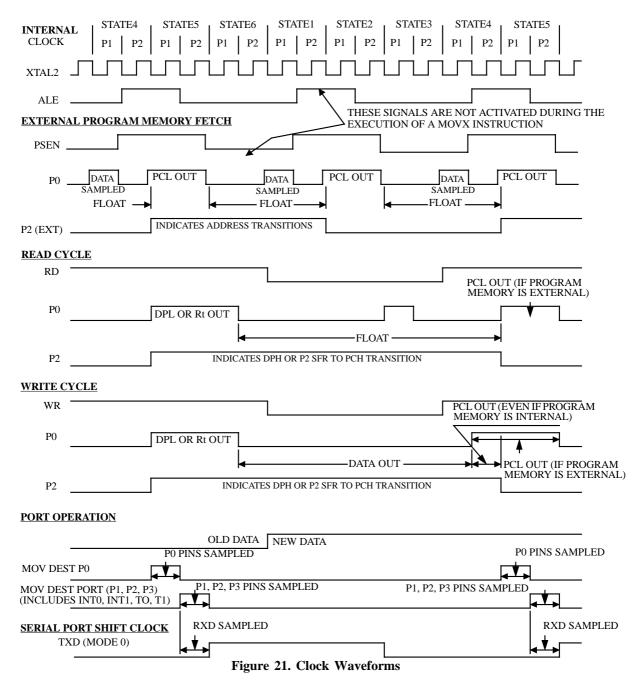
Rev. C - 15 January, 2001



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OL}/I_{OH} \ge \pm 20$ mA.

7.5.13 Clock Waveforms

Valid in normal clock mode. In X2 mode XTAL2 signal must be changed to XTAL2 divided by two.



This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though (T_A =25°C fully loaded) \overline{RD} and \overline{WR} propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.



8. Ordering Information

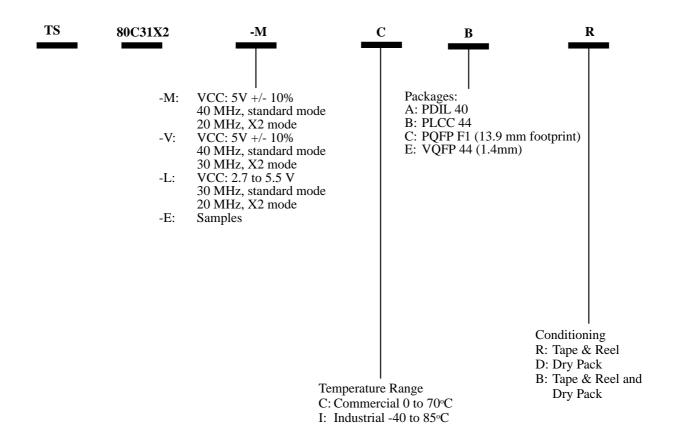


Table 28. Maximum Clock Frequency

Code	-M	-V	-L	Unit
Standard Mode, oscillator frequency	40	40	30	MHz
Standard Mode, internal frequency	40	40	30	
X2 Mode, oscillator frequency	20	30	20	MHz
X2 Mode, internal equivalent frequency	40	60	40	

Rev. C - 15 January, 2001 41



Table 29. Possible Ordering Entries

	TS80C31X2 ROMless
-MCA	X
-MCB	X
-MCC	X
-MCE	X
-VCA	X
-VCB	X
-VCC	X
-VCE	X
-LCA	X
-LCB	X
-LCC	X
-LCE	X
-MIA	X
-MIB	X
-MIC	X
-MIE	X
-VIA	X
-VIB	X
-VIC	X
-VIE	X
-LIA	X
-LIB	X
-LIC	X
-LIE	X
-EA	X
-EB	X
-EC	X
-EE	X

- -Ex for samples
- Tape and Reel available for B, C and E packages
- Dry pack mandatory for E packages